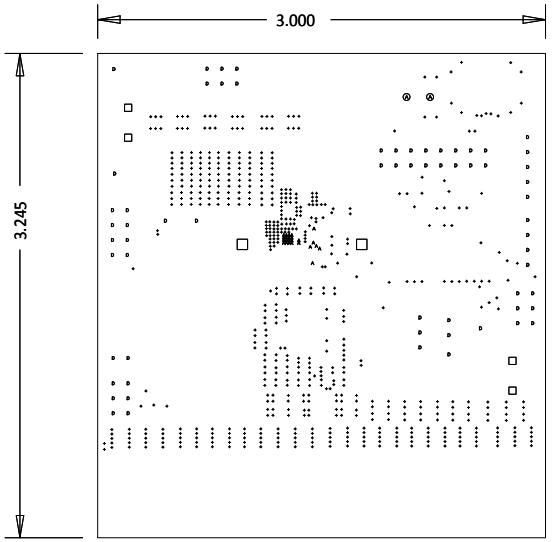
REVISIONS			
REV	DESCRIPTION	APPROVED	DATE
A	RELEASE		

NOTES:

1. Specifications
1.0 Fabricate per IPC-A-600 and IPC-6012
1.1 Producibility study - It is the responsibility of the supplier to conduct a thorough review of the artwork and media for manufacturability in the supplier's process compliance to all applicable specifications. Volterra must be advised in writing (in advance of manufacturing) of any changes, revisions, or corrections made or recommendations to ensure conformance to Volterr standards, and of any specifications that cannot be met.
1.2 This drawing is to be used in conjunction with the provided gerber and drill data when applicable.
1.3 All notes are "Unless Otherwise Specified."
2. Material
2.0 Per IPC-4101A/24/26/29/98
2.1 Copper clad high temperature FR4 Class epoxy glass Rated UL94V-0.
2.2 Must be ROHS compliant and survive a Lead Free assembly, maximum reflow of 260 deress C (6 Passes)
2.3 Td rating:>340 degrees C
2.4 Z axis CTE <3.5%
2.5 Tg (for reference only) choose from:
>150 degrees C (min.) for 8 layers or less
>170 degrees C (min.) for > 8 layers
3. Solder mask
3.0 Solder mask both sides with (GREEN color) liquid photoimageable solder mask, 003 max, thickness.
4. Drilling
4.0 All hole diameters are finished sizes.
4.1 All holes to be +/- .003 from true position unless otherwise specified.
4.2 All hole diameters to be +/- .003 unless otherwise specified.
4.3 An NC drill file has been supplied - see drill table.
5. Plating and Finishing
5.0 Plate thu holes with copper .002" min. thickness drill size dimension apply after plating.
5.1 Finish coat exposed copper using OSP
5.2 Finished boards shall not have nicks, scratches, voids, exposed copper, poor plating, or misdrilled holes.
5.3 .006 nominal trace width, .005 minimum trace width.
5.4 Plate fingers with .000030" gold over .000100" nickel
5.5 Copper thickness per 'PCB CROSS SECTION'
6. Silkscreen
6.0 Silkscreen using white non-conductive epoxy or equivalent.
6.1 No silkscreen allowed on exposed lands or in holess which are open on solder mask layers.
6.2 Silkscreen must be a minimum of 3mm away from fiducial marks.
6.3 Minimum clearance between silkscreen legend and vias, pads, or holes to be .005.
6.4 Registration to be +/- .005 and must pass peel test.
7. Electrical Test
7.0 All boards shall be 100% electronically tested for opens/short at 10 volts.
7.1 Apply test stamp in non-legend area on solder side of PCB.
8. Cleanliness
8.0 Boards shall be free of fiberglass dust or any other foreign material.
8.1 Finished boards must conform to 0.01 MG/IN max Nacl ionic contamination as measured by the omega meter 600SMD. with sufficient surrounding material to prevent shipping damage.
9. Packaging
9.0 There shall be a max of 10 units per package, individually wrapped, and shipped in cardboard cartons
9.1 All individual packages must be labeled with the following:
Maxim Part Number
Fab Date Code
QTY
Finish
Rohs Compliant
10. Bow and Twist
10.0 Bow and twist to be .007 IN/IN or .090 max according to IPC-A600D.
11. Inspection
11.0 Automatic optical inspection of all layers required.
12. .5mm pitch QFN component pad requirements: (If Applicable)
12.0 Solder mask alignment to each pad footprint area +/- .002 in respect to true position.
12.1 Maxim QFN devices are solder defined.
12.2 Solder mask pad openings shall not expose pad edge or bare FR-4.
13. RoHS
13.1 This board to be RoHS compliant.

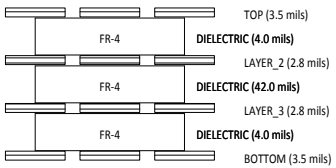


DRILL CHART: TOP to BOTTOM

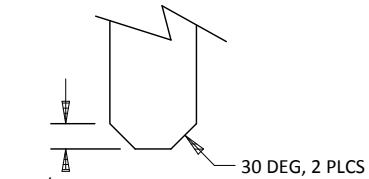
ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
*	8.0	+2.0/-2.0	PLATED	613
A	8.0	+3.0/-3.0	PLATED	24
B	40.0	+3.0/-3.0	PLATED	64
□	48.0	+3.0/-3.0	PLATED	4
□	70.0	+3.0/-3.0	PLATED	2
Ⓐ	47.0	+3.0/-3.0	NON-PLATED	2

4 Layer Board -- All Cu Thickness is Final +.0007/-.0000



TOTAL THICKNESS: 62.6 mils +/-10%



DETAIL A

SCALE: NONE

TOLERANCES UNLESS OTHERWISE SPECIFIED

FRACTIONS +/- 1/64 | DECIMALS .XX +/- .01, .XXX +/- .005 | ANGLES +/- 1/2

MATERIAL: SEE NOTES

FINISH: SEE NOTES

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APPR. BY: BSUPPANZ	DATE: 04/30/15	
APPR. BY:	DATE:	

maxim integrated™

TITLE:
FABRICATION DWG.
MAX20730/45 EVAL BOARD

SIZE	DRAWING NO.	REV
E	35-900384-00-00	A
NOT TO SCALE	TEMPLATE REV 1.5	SHEET 1 OF 1